

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Koichi Uchiyama
Serial No. : Unknown
Filed : Herewith
Title : STENCIL SHEET, PROCESS FOR
PRODUCING THE SAME, AND PROCESS FOR
PRODUCING STENCIL PLATE

Attorney Docket : KAW 2 0102

Assistant Commissioner For Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Dear Sir:

Prior to substantive examination of the above-identified patent application, please amend the application as follows:

IN THE CLAIMS:

Please amend claims 3-6, and 9-13 as follows:

3. (Amended) The stencil sheet according to claim 1 wherein the area fraction of the opening portions of said minute perforations is in the range of 20 to 70 % and the diameters of equivalent circles are in the range of 5 to 200 μm when the opening portions are assumed to be circular in shape.

4. (Amended) The stencil sheet according to claim 1 wherein said minute perforations in said sheet are trapezoidal in vertical cross section.

5. (Amended) The stencil sheet according to claim 1 wherein the thickness of said sheet is in the range of 1.5 to 20 μm .

"Express Mail" Mailing Label Number 8654579501905
Date of Deposit Jan 17, 2002
I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.
Pamela Steed
(TYPED OR PRINTED NAME OF SENDER)
Pamela Steed
(SIGNATURE)

6. (Amended) The stencil sheet according to claim 1 wherein said stencil sheet further comprises a porous support laminated on one side of said sheet.

9. (Amended) The process for producing a stencil sheet according to claim 7 wherein the process further comprises laminating a porous support on one side of said film after a roller having drill-like projections formed on its surface was pressed against said film of a synthetic resin to form minute perforations and said minute perforations were filled with said filler or resin.

10. (Amended) The process for producing a stencil sheet according to claim 7 wherein said filler or resin is selected from the group consisting of the following resins (A), (B), and (C).

- (A) a resin having a melting point lower than that of said film
- (B) a resin which is soluble in a solvent
- (C) a heat adhesive resin

11. (Amended) The process for producing a stencil sheet according to claim 7 wherein said film has an area fraction of the opening portions of said minute perforations in the range of 20 to 70 % and diameters of equivalent circles in the range of 5 to 200 μm when the opening portions are assumed to be circular in shape.

12. (Amended) The process for producing a stencil sheet according to claim 7 wherein the minute perforations in said film are trapezoidal in vertical cross section.

13. (Amended) The process for producing a stencil sheet according to claim 7 or 8 wherein said film has a thickness in the range of 1.5 to 20 μm .

Please add new claims 15-20 as follows:

15. The stencil sheet according to claim 2 wherein the area fraction of the opening portions of said minute perforations is in the range of 20 to 70 % and the diameters of equivalent circles are in the range of 5 to 200 μm when the opening portions are assumed to be circular in shape.

16. The stencil sheet according to claim 2 wherein said minute perforations in said sheet are trapezoidal in vertical cross section.

17. The stencil sheet according to claim 2 wherein the thickness of said sheet is in the range of 1.5 to 20 μm .

18. The stencil sheet according to claim 2 wherein said stencil sheet further comprises a porous support laminated on one side of said sheet.

19. The process for producing a stencil sheet according to claim 8 wherein the process further comprises laminating a porous support on one side of said film after a roller having drill-like projections formed on its surface was pressed against said film of a synthetic resin to form minute perforations and said minute perforations were filled with said filler or resin.

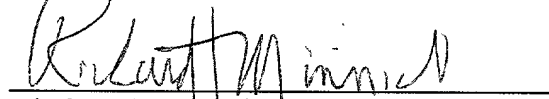
20. The process for producing a stencil sheet according to claim 8 wherein said filler or resin is selected from the group consisting of the following resins (A), (B), and (C).

- (A) a resin having a melting point lower than that of said film
- (B) a resin which is soluble in a solvent
- (C) a heat adhesive resin

REMARKS

It is respectfully submitted that the subject application is now in better condition for examination.

Respectfully submitted,



Richard J. Minnich

Reg. No. 24,175

FAY, SHARPE, FAGAN,
MINNICH & MCKEE, LLP
1100 Superior Avenue
Seventh Floor
Cleveland, Ohio 44114-2518
(216) 861-5582

VERSION WITH MARKINGS SHOWING CHANGES MADE

3. (Amended) The stencil sheet according to claim 1 [or 2] wherein the area fraction of the opening portions of said minute perforations is in the range of 20 to 70 % and the diameters of equivalent circles are in the range of 5 to 200 μm when the opening portions are assumed to be circular in shape.

4. (Amended) The stencil sheet according to claim 1 [or 2] wherein said minute perforations in said sheet are trapezoidal in vertical cross section.

5. (Amended) The stencil sheet according to claim 1 [or 2] wherein the thickness of said sheet is in the range of 1.5 to 20 μm .

6. (Amended) The stencil sheet according to claim 1 [or 2] wherein said stencil sheet further comprises a porous support laminated on one side of said sheet.

9. (Amended) The process for producing a stencil sheet according to claim 7 [or 8] wherein the process further comprises laminating a porous support on one side of said film after a roller having drill-like projections formed on its surface was pressed against said film of a synthetic resin to form minute perforations and said minute perforations were filled with said filler or resin.

10. (Amended) The process for producing a stencil sheet according to claim 7 [or 8] wherein said filler or resin is selected from the group consisting of the following resins (A), (B), and (C).

(A) a resin having a melting point lower than that of said film

- (B) a resin which is soluble in a solvent
- (C) a heat adhesive resin

11. (Amended) The process for producing a stencil sheet according to claim 7 [or 8] wherein said film has an area fraction of the opening portions of said minute perforations in the range of 20 to 70 % and diameters of equivalent circles in the range of 5 to 200 μm when the opening portions are assumed to be circular in shape.

12. (Amended) The process for producing a stencil sheet according to claim 7 [or 8] wherein the minute perforations in said film are trapezoidal in vertical cross section.

13. (Amended) The process for producing a stencil sheet according to claim 7 or 8 wherein said film has a thickness in the range of 1.5 to 20 μm .